MC33260

GreenLine™ Compact Power Factor Controller: Innovative Circuit for Cost Effective Solutions

The MC33260 is a controller for Power Factor Correction preconverters meeting international standard requirements in electronic ballast and off-line power conversion applications. Designed to drive a free frequency discontinuous mode, it can also be synchronized and in any case, it features very effective protections that ensure a safe and reliable operation.

This circuit is also optimized to offer extremely compact and cost effective PFC solutions. While it requires a minimum number of external components, the MC33260 can control the follower boost operation that is an innovative mode allowing a drastic size reduction of both the inductor and the power switch. Ultimately, the solution system cost is significantly lowered.

Also able to function in a traditional way (constant output voltage regulation level), any intermediary solutions can be easily implemented. This flexibility makes it ideal to optimally cope with a wide range of applications.

General Features

- Standard Constant Output Voltage or “Follower Boost” Mode
- Switch Mode Operation: Voltage Mode
- Latching PWM for Cycle-by-Cycle On-Time Control
- Constant On-Time Operation That Saves the Use of an Extra Multiplier
- Totem Pole Output Gate Drive
- Undervoltage Lockout with Hysteresis
- Low Startup and Operating Current
- Improved Regulation Block Dynamic Behavior
- Synchronization Capability
- Internally Trimmed Reference Current Source
- These are Pb-Free Devices

Safety Features

- Overvoltage Protection: Output Overvoltage Detection
- Undervoltage Protection: Protection Against Open Loop
- Effective Zero Current Detection
- Accurate and Adjustable Maximum On-Time Limitation
- Overcurrent Protection
- ESD Protection on Each Pin

Figure 1. Typical Application

ORDERING INFORMATION
See detailed ordering and shipping information in the package dimensions section on page 20 of this data sheet.
Figure 2. Block Diagram
MAXIMUM RATINGS

<table>
<thead>
<tr>
<th>Rating</th>
<th>Pin #</th>
<th>Pin #</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Gate Drive Current*</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Source</td>
<td>7</td>
<td>5</td>
<td>$I_{O\text{ (Source) }}$</td>
<td>-500</td>
<td>mA</td>
</tr>
<tr>
<td>Sink</td>
<td></td>
<td></td>
<td>$I_{O\text{ (Sink) }}$</td>
<td>500</td>
<td></td>
</tr>
<tr>
<td>$V_{CC}$ Maximum Voltage</td>
<td>8</td>
<td>6</td>
<td>$(V_{cc})_{\text{max}}$</td>
<td>16</td>
<td>V</td>
</tr>
<tr>
<td>Input Voltage</td>
<td></td>
<td></td>
<td>$V_{in}$</td>
<td>-0.3 to +10</td>
<td>V</td>
</tr>
<tr>
<td>Power Dissipation and Thermal Characteristics</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>P Suffix, PDIP Package</td>
<td></td>
<td></td>
<td>$P_D$</td>
<td>600</td>
<td>mW/C/W</td>
</tr>
<tr>
<td>Thermal Resistance Junction-to-Air</td>
<td></td>
<td></td>
<td>$R_{JA}$</td>
<td>100</td>
<td></td>
</tr>
<tr>
<td>Operating Junction Temperature</td>
<td></td>
<td></td>
<td>$T_J$</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Ambient Temperature</td>
<td></td>
<td></td>
<td>$T_A$</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS ($V_{CC} = 13$ V, $T_J = 25^\circ$C for typical values, $T_J = -40$ to $105^\circ$C for min/max values unless otherwise noted.)

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Pin #</th>
<th>Pin #</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>GATE DRIVE SECTION</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gate Drive Resistor</td>
<td>7</td>
<td>5</td>
<td>$R_{OL}$</td>
<td>10</td>
<td>20</td>
<td>35</td>
<td>Ω</td>
</tr>
<tr>
<td>Source Resistor @ $I_{drive} = 100$ mA</td>
<td></td>
<td></td>
<td>$R_{OH}$</td>
<td>5</td>
<td>10</td>
<td>25</td>
<td></td>
</tr>
<tr>
<td>Sink Resistor @ $I_{drive} = 100$ mA</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gate Drive Voltage Rise Time (From 3.0 V Up to 9.0 V) (Note 1)</td>
<td>7</td>
<td>5</td>
<td>$t_r$</td>
<td>-</td>
<td>50</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>Output Voltage Falling Time (From 9.0 V Down to 3.0 V) (Note 1)</td>
<td>7</td>
<td>5</td>
<td>$t_f$</td>
<td>-</td>
<td>50</td>
<td>-</td>
<td>ns</td>
</tr>
</tbody>
</table>

OSCILLATOR SECTION

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Pin #</th>
<th>Pin #</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Maximum Oscillator Swing</td>
<td>3</td>
<td>1</td>
<td>$\Delta V_T$</td>
<td>1.4</td>
<td>1.5</td>
<td>1.6</td>
<td>V</td>
</tr>
<tr>
<td>Charge Current @ $I_{FB} = 100$ μA</td>
<td>3</td>
<td>1</td>
<td>$I_{charge}$</td>
<td>87.5</td>
<td>100</td>
<td>112.5</td>
<td>μA</td>
</tr>
<tr>
<td>Charge Current @ $I_{FB} = 200$ μA</td>
<td>3</td>
<td>1</td>
<td>$I_{charge}$</td>
<td>350</td>
<td>400</td>
<td>450</td>
<td>μA</td>
</tr>
<tr>
<td>Ratio Multiplier Gain Over Maximum Swing @ $I_{FB} = 100$ μA</td>
<td>3</td>
<td>1</td>
<td>$K_{osc}$</td>
<td>5600</td>
<td>6400</td>
<td>7200</td>
<td>1/(V.A)</td>
</tr>
<tr>
<td>Ratio Multiplier Gain Over Maximum Swing @ $I_{FB} = 200$ μA</td>
<td>3</td>
<td>1</td>
<td>$K_{osc}$</td>
<td>5600</td>
<td>6400</td>
<td>7200</td>
<td>1/(V.A)</td>
</tr>
<tr>
<td>Average Internal Oscillator Pin Capacitance Over Oscillator Maximum Swing (C_T Voltage Varying From 0 Up to 1.5 V) (Note 2)</td>
<td>3</td>
<td>1</td>
<td>$C_{int}$</td>
<td>10</td>
<td>15</td>
<td>20</td>
<td>pF</td>
</tr>
<tr>
<td>Discharge Time (C_T = 1.0 nF)</td>
<td>3</td>
<td>1</td>
<td>$T_{disch}$</td>
<td>-</td>
<td>0.5</td>
<td>1.0</td>
<td>μS</td>
</tr>
</tbody>
</table>

REGULATION SECTION

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Pin #</th>
<th>Pin #</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Regulation High Current Reference</td>
<td>1</td>
<td>7</td>
<td>$I_{regH}$</td>
<td>192</td>
<td>200</td>
<td>208</td>
<td>μA</td>
</tr>
<tr>
<td>Ratio (Regulation Low Current Reference)/$I_{regH}$</td>
<td>1</td>
<td>7</td>
<td>$I_{regL}/I_{regH}$</td>
<td>0.965</td>
<td>0.97</td>
<td>0.98</td>
<td>-</td>
</tr>
<tr>
<td>$V_{control}$ Impedance</td>
<td>1</td>
<td>7</td>
<td>$Z_{V_{control}}$</td>
<td>-</td>
<td>300</td>
<td>-</td>
<td>kΩ</td>
</tr>
</tbody>
</table>

NOTE: $I_{FB}$ is the current that is drawn by the Feedback Input Pin.
1. 1.0 nF being connected between the Pin 7 and ground for PDIP-8, between Pin 5 and ground for SO-8.
2. Guaranteed by design.
## ELECTRICAL CHARACTERISTICS

(V\textsubscript{CC} = 13 V, T\textsubscript{J} = 25°C for typical values, T\textsubscript{J} = -40 to 105°C for min/max values unless otherwise noted.)

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Pin # PDIP-8</th>
<th>Pin # SO-8</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>REGULATION SECTION (continued)</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Feedback Pin Clamp Voltage @ I\textsubscript{FB} = 100 \mu A</td>
<td>1</td>
<td>7</td>
<td>V\textsubscript{FB-100}</td>
<td>1.5</td>
<td>2.1</td>
<td>2.5</td>
<td>V</td>
</tr>
<tr>
<td>Feedback Pin Clamp Voltage @ I\textsubscript{FB} = 200 \mu A</td>
<td>1</td>
<td>7</td>
<td>V\textsubscript{FB-200}</td>
<td>2.0</td>
<td>2.6</td>
<td>3.0</td>
<td>V</td>
</tr>
<tr>
<td><strong>CURRENT SENSE SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Zero Current Detection Comparator Threshold</td>
<td>4</td>
<td>2</td>
<td>V\textsubscript{ZCD-th}</td>
<td>-90</td>
<td>-60</td>
<td>-30</td>
<td>mV</td>
</tr>
<tr>
<td>Negative Clamp Level (I\textsubscript{CS-pin} = -1.0 mA)</td>
<td>4</td>
<td>2</td>
<td>Cl-neg</td>
<td>-</td>
<td>-0.7</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>Bias Current @ V\textsubscript{CS} = V\textsubscript{ZCD-th}</td>
<td>4</td>
<td>2</td>
<td>I\textsubscript{b-cs}</td>
<td>-0.2</td>
<td>-</td>
<td>-</td>
<td>\mu A</td>
</tr>
<tr>
<td>Propagation Delay (V\textsubscript{CS} &gt; V\textsubscript{ZCD-th}) to Gate Drive High</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{ZCD}</td>
<td>-</td>
<td>500</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>Current Sense Internal Current Source</td>
<td>4</td>
<td>2</td>
<td>I\textsubscript{OCP}</td>
<td>192</td>
<td>205</td>
<td>218</td>
<td>\mu A</td>
</tr>
<tr>
<td>Leading Edge Blanking Duration</td>
<td></td>
<td></td>
<td>t\textsubscript{LEB}</td>
<td>-</td>
<td>400</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>OverCurrent Protection Propagation Delay (V\textsubscript{CS} &lt; V\textsubscript{ZCD-th} to Gate Drive Low)</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{OCP}</td>
<td>100</td>
<td>160</td>
<td>240</td>
<td>ns</td>
</tr>
<tr>
<td><strong>SYNCHRONIZATION SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Synchronization Threshold PDIP-8</td>
<td>5</td>
<td>-</td>
<td>V\textsubscript{sync-th}</td>
<td>0.8</td>
<td>1.0</td>
<td>1.2</td>
<td>V</td>
</tr>
<tr>
<td>SO-8</td>
<td>3</td>
<td>V\textsubscript{sync-th}</td>
<td>0.8</td>
<td>1.0</td>
<td>1.4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Negative Clamp Level (I\textsubscript{sync} = -1.0 mA)</td>
<td>5</td>
<td>3</td>
<td>Cl-neg</td>
<td>-</td>
<td>-0.7</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>Minimum Off-Time</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{off}</td>
<td>1.5</td>
<td>2.1</td>
<td>2.7</td>
<td>\mu s</td>
</tr>
<tr>
<td>Minimum Required Synchronization Pulse Duration</td>
<td>5</td>
<td>3</td>
<td>T\textsubscript{sync}</td>
<td>-</td>
<td>-</td>
<td>0.5</td>
<td>\mu s</td>
</tr>
<tr>
<td><strong>OVERVOLTAGE PROTECTION SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>OverVoltage Protection High Current Threshold and I\textsubscript{regH} Difference</td>
<td>1</td>
<td>7</td>
<td>I\textsubscript{OVPH-IregH}</td>
<td>8.0</td>
<td>13</td>
<td>18</td>
<td>\mu A</td>
</tr>
<tr>
<td>OverVoltage Protection Low Current Threshold and I\textsubscript{regH} Difference</td>
<td>1</td>
<td>7</td>
<td>I\textsubscript{OVPL-IregH}</td>
<td>0</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>Ratio (I\textsubscript{OVPH}/I\textsubscript{OVPL})</td>
<td>1</td>
<td>7</td>
<td>I\textsubscript{OVPH}/I\textsubscript{OVPL}</td>
<td>1.02</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>Propagation Delay (I\textsubscript{FB} &gt; 110% I\textsubscript{ref} to Gate Drive Low)</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{OVP}</td>
<td>-</td>
<td>500</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td><strong>UNDERVOLTAGE PROTECTION SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Ratio (UnderVoltage Protection Current Threshold)/I\textsubscript{regH}</td>
<td>1</td>
<td>7</td>
<td>I\textsubscript{UVP}/I\textsubscript{regH}</td>
<td>12</td>
<td>14</td>
<td>16</td>
<td>%</td>
</tr>
<tr>
<td>Propagation Delay (I\textsubscript{FB} &lt; 12% I\textsubscript{ref} to Gate Drive Low)</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{UVP}</td>
<td>-</td>
<td>500</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td><strong>THERMAL SHUTDOWN SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Thermal Shutdown Threshold</td>
<td>7</td>
<td>5</td>
<td>T\textsubscript{stdwn}</td>
<td>-</td>
<td>150</td>
<td>-</td>
<td>°C</td>
</tr>
<tr>
<td>Hysteresis</td>
<td>7</td>
<td>5</td>
<td>ΔT\textsubscript{stdwn}</td>
<td>-</td>
<td>30</td>
<td>-</td>
<td>°C</td>
</tr>
<tr>
<td><strong>V\textsubscript{CC} UNDERVOLTAGE LOCKOUT SECTION</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Startup Threshold</td>
<td>8</td>
<td>6</td>
<td>V\textsubscript{stup-th}</td>
<td>9.7</td>
<td>11</td>
<td>12.3</td>
<td>V</td>
</tr>
<tr>
<td>Disable Voltage After Threshold Turn-On</td>
<td>8</td>
<td>6</td>
<td>V\textsubscript{disable}</td>
<td>7.4</td>
<td>8.5</td>
<td>9.6</td>
<td>V</td>
</tr>
<tr>
<td><strong>TOTAL DEVICE</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Power Supply Current</td>
<td>8</td>
<td>6</td>
<td>I\textsubscript{CC}</td>
<td>-</td>
<td>0.1</td>
<td>0.25</td>
<td>mA</td>
</tr>
<tr>
<td>Startup (V\textsubscript{CC} = 5 V with V\textsubscript{CC} Increasing)</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating @ I\textsubscript{FB} = 200 \mu A</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

NOTE: V\textsubscript{CS} is the Current Sense Pin Voltage and I\textsubscript{FB} is the Feedback Pin Current.
Pin Numbers are Relevant to the PDIP-8 Version

Figure 3. Regulation Block Output versus Feedback Current

Figure 4. Regulation Block Output versus Feedback Current

Figure 5. Maximum Oscillator Swing versus Temperature

Figure 6. Feedback Input Voltage versus Feedback Current

Figure 7. Oscillator Charge Current versus Feedback Current

Figure 8. Oscillator Charge Current versus Temperature
Pin Numbers are Relevant to the PDIP-8 Version

Figure 9. Oscillator Charge Current versus Temperature

Figure 10. On-Time versus Feedback Current

Figure 11. On-Time versus Feedback Current

Figure 12. Internal Current Sources versus Temperature

Figure 13. $(I_{OVPH}/I_{REF}), (I_{OVP/L}/I_{REF}), (I_{REGL}/I_{REF})$ versus Temperature

Figure 14. Undervoltage Ratio versus Temperature
Pin Numbers are Relevant to the PDIP-8 Version

Figure 15. Current Sense Threshold versus Temperature

Figure 16. Circuit Consumption versus Supply Voltage

Figure 17. Oscillator Pin Internal Capacitance

Figure 18. Gate Drive Cross Conduction

Figure 19. Gate Drive Cross Conduction

Figure 20. Gate Drive Cross Conduction
### PIN FUNCTION DESCRIPTION

<table>
<thead>
<tr>
<th>Pin #</th>
<th>Pin #</th>
<th>Function</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>7</td>
<td>Feedback Input</td>
<td>This pin is designed to receive a current that is proportional to the preconverter output voltage. This information is used for both the regulation and overvoltage and undervoltage protections. The current drawn by this pin is internally squared to be used as oscillator capacitor charge current.</td>
</tr>
<tr>
<td>2</td>
<td>8</td>
<td>$V_{\text{control}}$</td>
<td>This pin makes available the regulation block output. The capacitor connected between this pin and ground, adjusts the control bandwidth. It is typically set below 20 Hz to obtain a nondistorted input current.</td>
</tr>
<tr>
<td>3</td>
<td>1</td>
<td>Oscillator Capacitor ($C_T$)</td>
<td>The circuit uses an on-time control mode. This on-time is controlled by comparing the $C_T$ voltage to the $V_{\text{control}}$ voltage. $C_T$ is charged by the squared feedback current.</td>
</tr>
<tr>
<td>4</td>
<td>2</td>
<td>Zero Current Detection Input</td>
<td>This pin is designed to receive a negative voltage signal proportional to the current flowing through the inductor. This information is generally built using a sense resistor. The Zero Current Detection prevents any restart as long as the Pin 4 voltage is below (-60 mV). This pin is also used to perform the peak current limitation. The overcurrent threshold is programmed by the resistor connected between the pin and the external current sense resistor.</td>
</tr>
<tr>
<td>5</td>
<td>3</td>
<td>Synchronization Input</td>
<td>This pin is designed to receive a synchronization signal. For instance, it enables to synchronize the PFC preconverter to the associated SMPS. If not used, this pin must be grounded.</td>
</tr>
<tr>
<td>6</td>
<td>4</td>
<td>Ground</td>
<td>This pin must be connected to the preregulator ground.</td>
</tr>
<tr>
<td>7</td>
<td>5</td>
<td>Gate Drive</td>
<td>The gate drive current capability is suited to drive an IGBT or a power MOSFET.</td>
</tr>
<tr>
<td>8</td>
<td>6</td>
<td>$V_{\text{CC}}$</td>
<td>This pin is the positive supply of the IC. The circuit turns on when $V_{\text{CC}}$ becomes higher than 11 V, the operating range after startup being 8.5 V up to 16 V.</td>
</tr>
</tbody>
</table>

![Application Schematic](http://onsemi.com)

**Figure 21. Application Schematic**
INTRODUCTION

The need of meeting the requirements of legislation on line current harmonic content, results in an increasing demand for cost effective solutions to comply with the Power Factor regulations. This data sheet describes a monolithic controller specially designed for this purpose.

Most off-line appliances use a bridge rectifier associated to a huge bulk capacitor to derive raw dc voltage from the utility ac line.

This technique results in a high harmonic content and in poor power factor ratios. In effect, the simple rectification technique draws power from the mains when the instantaneous ac voltage exceeds the capacitor voltage. This occurs near the line voltage peak and results in a high charge current spike. Consequently, a poor power factor (in the range of 0.5 - 0.7) is generated, resulting in an apparent input power that is much higher than the real power.

Active solutions are the most popular way to meet the legislation requirements. They consist of inserting a PFC pre-regulator between the rectifier bridge and the bulk capacitor. This interface is, in fact, a step-up SMPS that outputs a constant voltage while drawing a sinusoidal current from the line.

The MC33260 was developed to control an active solution with the goal of increasing its robustness while lowering its global cost.

OPERATION DESCRIPTION

The MC33260 is optimized to just as well drive a free running as a synchronized discontinuous voltage mode.

It also features valuable protections (overvoltage and undervoltage protection, overcurrent limitation, ...) that make the PFC preregulator very safe and reliable while requiring very few external components. In particular, it is able to safely face any uncontrolled direct charges of the output capacitor from the mains which occur when the output voltage is lower than the input voltage (startup, overload, ...).

In addition to the low count of elements, the circuit can control an innovative mode named “Follower Boost” that permits to significantly reduce the size of the preconverter inductor and power MOSFET. With this technique, the output regulation level is not forced to a constant value, but can vary according to the a.c. line amplitude and to the power. The gap between the output voltage and the ac line is then lowered, what allows the preconverter inductor and power MOSFET size reduction. Finally, this method brings a significant cost reduction.

A description of the functional blocks is given below.

REGULATION SECTION

Connecting a resistor between the output voltage to be regulated and the Pin 1, a feedback current is obtained. Typically, this current is built by connecting a resistor between the output voltage and the Pin 1. Its value is then given by the following equation:

\[ I_{\text{pin1}} = \frac{V_o - V_{\text{pin1}}}{R_o} \]

where:
- \( R_o \) is the feedback resistor,
- \( V_o \) is the output voltage,
- \( V_{\text{pin1}} \) is the Pin 1 clamp value.

The feedback current is compared to the reference current so that the regulation block outputs a signal following the characteristic depicted in Figure 25. According to the power and the input voltage, the output voltage regulation level varies between two values \((V_o)_{\text{regL}}\) and \((V_o)_{\text{regH}}\) corresponding to the \(I_{\text{regL}}\) and \(I_{\text{regH}}\) levels.

The feedback resistor must be chosen so that the feedback current should equal the internal current source \(I_{\text{regH}}\) when the output voltage exceeds the chosen upper regulation voltage \((V_o)_{\text{regH}}\).
Consequently:

\[ R_o = \frac{(V_o)_{\text{regH}} - V_{\text{pin1}}}{I_{\text{regH}}} \]

In practice, \( V_{\text{pin1}} \) is small compared to \( (V_o)_{\text{regH}} \) and this equation can be simplified as follows (\( I_{\text{regH}} \) being also replaced by its typical value 200 \( \mu \)A):

\[ R_o \approx 5 \times \frac{(V_o)_{\text{regH}}}{V_{\text{pin1}}} \text{ (k\Omega)} \]

The regulation block output is connected to the Pin 2 through a 300 k\( \Omega \) resistor. The Pin 2 voltage (\( V_{\text{control}} \)) is compared to the oscillator sawtooth for PWM control.

An external capacitor must be connected between Pin 2 and ground, for external loop compensation. The bandwidth is typically set below 20 Hz so that the regulation block output should be relatively constant over a given ac line cycle. This integration that results in a constant on-time over the ac line period, prevents the mains frequency output ripple from distorting the ac line current.

**OSCILLATOR SECTION**

The oscillator consists of three phases:

- **Charge Phase:** The oscillator capacitor voltage grows linearly from its bottom value (ground) until it exceeds \( V_{\text{control}} \) (regulation block output voltage). At that moment, the PWM latch output gets low and the oscillator discharge sequence is set.
- **Discharge Phase:** The oscillator capacitor is abruptly discharged down to its valley value (0 V).
- **Waiting Phase:** At the end of the discharge sequence, the oscillator voltage is maintained in a low state until the PWM latch is set again.

![Figure 26. Oscillator](image)

The oscillator charge current is dependent on the feedback current (\( I_o \)). In effect

\[ I_{\text{charge}} = 2 \times I_0 \times I_0 / I_{\text{ref}} \]

where:

- \( I_{\text{charge}} \) is the oscillator charge current
- \( I_0 \) is the feedback current (drawn by Pin 1)
- \( I_{\text{ref}} \) is the internal reference current (200 \( \mu \)A).

So, the oscillator charge current is linked to the output voltage level as follows:

\[ I_{\text{charge}} = \frac{2 \times (V_0 - V_{\text{pin1}})^2}{R_o^2 \times I_{\text{ref}}} \]

where:

- \( V_0 \) is the output voltage
- \( R_o \) is the feedback resistor
- \( V_{\text{pin1}} \) is the Pin 1 clamp voltage.

In practice, \( V_{\text{pin1}} \) that is in the range of 2.5 V, is very small compared to \( V_0 \). The equation can then be simplified by neglecting \( V_0 \):

\[ I_{\text{charge}} \approx \frac{2 \times V_0^2}{R_o^2 \times I_{\text{ref}}} \]

It must be noticed that the oscillator terminal (Pin 3) has an internal capacitance (\( C_{\text{int}} \)) that varies versus the Pin 3 voltage. Over the oscillator swing, its average value typically equals 15 pF (min 10 pF, max 20 pF).

The total oscillator capacitor is then the sum of the internal and external capacitors.

\[ C_{\text{pin3}} = C_T + C_{\text{int}} \]

**PWM LATCH SECTION**

The MC33260 operates in voltage mode: the regulation block output (\( V_{\text{control}} - \) Pin 2 voltage) is compared to the oscillator sawtooth so that the gate drive signal (Pin 7) is high until the oscillator ramp exceeds \( V_{\text{control}} \).

The on-time is then given by the following equation:

\[ t_{\text{on}} = \frac{C_{\text{pin3}} \times V_{\text{control}}}{I_{\text{ch}}} \]

where:

- \( t_{\text{on}} \) is the on-time
- \( C_{\text{pin3}} \) is the total oscillator capacitor (sum of the internal and external capacitor)
- \( I_{\text{charge}} \) is the oscillator charge current (Pin 3 current)
- \( V_{\text{control}} \) is the Pin 2 voltage (regulation block output)

Consequently, replacing \( I_{\text{charge}} \) by the expression given in the **Oscillator Section**:

\[ t_{\text{on}} = \frac{R_o^2 \times I_{\text{ref}} \times C_{\text{pin3}} \times V_{\text{control}}}{2 \times V_0^2} \]

One can notice that the on-time depends on \( V_0 \) (preconverter output voltage) and that the on-time is maximum when \( V_{\text{control}} \) is maximum (1.5 V typically). At a given \( V_0 \), the maximum on-time is then expressed by the following equation:

\[ (t_{\text{on}})_{\text{max}} = \frac{C_{\text{pin3}} \times R_o^2 \times I_{\text{ref}} \times (V_{\text{control}})_{\text{max}}}{2 \times V_0^2} \]

This equation can be simplified replacing

\[ \left( \frac{2}{(V_{\text{control}})_{\text{max}} \cdot I_{\text{ref}}} \right) \]

by \( K_{\text{osc}} \)

Refer to **Electrical Characteristics, Oscillator Section**.

Then:

\[ (t_{\text{on}})_{\text{max}} = \frac{C_{\text{pin3}} \times R_o^2}{K_{\text{osc}} \times V_0^2} \]
This equation shows that the maximum on-time is inversely proportional to the squared output voltage. This property is used for follower boost operation (refer to **Follower Boost** section).

**CURRENT SENSE BLOCK**

The inductor current is converted into a voltage by inserting a ground referenced resistor \( R_{cs} \) in series with the input diodes bridge (and the input filtering capacitor). Therefore a negative voltage proportional to the inductor current is built:

\[
V_{cs} = -(R_{cs} \times I_L)
\]

where:
- \( I_L \) is the inductor current,
- \( R_{cs} \) is the current sense resistor,
- \( V_{cs} \) is the measured \( R_{cs} \) voltage.

**Zero Current Detection**

The Zero Current Detection function guarantees that the MOSFET cannot turn on as long as the inductor current hasn’t reached zero (discontinuous mode).

The Pin 4 voltage is simply compared to the (-60 mV) threshold so that as long as \( V_{cs} \) is lower than this threshold, the circuit gate drive signal is kept in low state. Consequently, no power MOSFET turn on is possible until the inductor current is measured as smaller than \( (60 \text{ mV}/R_{cs}) \) that is, the inductor current nearly equals zero.

![Figure 28. Current Sense Block](image)

**Overcurrent Protection**

During the power switch conduction (i.e. when the Gate Drive Pin voltage is high), a current source is applied to the Pin 4. A voltage drop \( V_{OCPP} \) is then generated across the resistor \( R_{OCP} \) that is connected between the sense resistor and the Current Sense Pin (refer to Figure 28). So, instead of \( V_{cs} \), the sum \( (V_{cs} + V_{OCPP}) \) is compared to (-60 mV) and the maximum permissible current is the solution of the following equation:

\[
-(R_{cs} \times I_{pkmax}) + V_{OCPP} = -60 \text{ mV}
\]

where:
- \( I_{pkmax} \) is maximum allowed current,
- \( R_{cs} \) is the sensing resistor.

The overcurrent threshold is then:

\[
I_{pkmax} = \frac{(R_{OCP} \times I_{OCP}) + 60 \times 10^{-3}}{R_{cs}}
\]

where:
- \( R_{OCP} \) is the resistor connected between the pin and the sensing resistor \( R_{cs} \),
- \( I_{OCP} \) is the current supplied by the Current Sense Pin when the gate drive signal is high (power switch conduction phase). \( I_{OCP} \) equals 205 \( \mu \text{A} \) typically.

Practically, the \( V_{OCPP} \) offset is high compared to 60 mV and the precedent equation can be simplified. The maximum current is then given by the following equation:

\[
I_{pkmax} = R_{OCP}(k\Omega) \times 0.205 \text{ (A)}
\]

Consequently, the \( R_{OCP} \) resistor can program the OCP level whatever the \( R_{cs} \) value is. This gives a high freedom in the choice of \( R_{cs} \). In particular, the inrush resistor can be utilized.

**Figure 27. Current Sensing**

The negative signal \( V_{cs} \) is applied to the current sense through a resistor \( R_{OCP} \). The pin is internally protected by a negative clamp (-0.7 V) that prevents substrate injection.

As long as the Pin 4 voltage is lower than (-60 mV), the Current Sense comparator resets the PWM latch to force the gate drive signal low state. In that condition, the power MOSFET cannot be on.

During the on-time, the Pin 4 information is used for the overcurrent limitation while it serves the zero current detection during the off time.
A LEB (Leading Edge Blanking) has been implemented. This circuitry disconnects the Current Sense comparator from Pin 4 and disables it during the 400 first ns of the power switch conduction. This prevents the block from reacting on the current spikes that generally occur at power switch turn on. Consequently, proper operation does not require any filtering capacitor on Pin 4.

**PROTECTIONS**

**OCP (Overcurrent Protection)**
Refer to Current Sense Block.

**OVP (Overvoltage Protection)**
The feedback current ($I_o$) is compared to a threshold current ($I_{ovpH}$). If it exceeds this value, the gate drive signal is maintained low until this current gets lower than a second level ($I_{ovpL}$).

![Figure 30. Internal Current Thresholds](image)

So, the OVP upper threshold is:

$$V_{ovpH} = V_{pin1} + \left( R_o \times I_{ovpH} \right)$$

where:
- $R_o$ is the feedback resistor that is connected between Pin 1 and the output voltage,
- $I_{ovpH}$ is the internal upper OVP current threshold,
- $V_{pin1}$ is the Pin 1 clamp voltage.

Practically, $V_{pin1}$ that is in the range of 2.5 V, can be neglected. The equation can then be simplified:

$$V_{ovpH} = R_o \times I_{ovpH} (\mu A) (V)$$

On the other hand, the OVP low threshold is:

$$V_{ovpL} = V_{pin1} + \left( R_o \times I_{ovpL} \right)$$

where $I_{ovpL}$ is the internal low OVP current threshold.

Consequently, $V_{pin1}$ being neglected:

$$V_{ovpL} = R_o \times I_{ovpL} (\mu A) (V)$$

The OVP hysteresis prevents erratic behavior. $I_{ovpL}$ is guaranteed to be higher than $I_{regH}$ (refer to parameters specification). This ensures that the OVP function doesn’t interfere with the regulation one.

**UVP (Undervoltage Protection)**
This function detects when the feedback current is lower than 14% of $I_{ref}$. In this case, the PWM latch is reset and the power switch is kept off.

This protection is useful to:
- Protect the preregulator from working in too low mains conditions.
- To detect the feedback current absence (in case of a nonproper connection for instance).

The UVP threshold is:

$$V_{uvp} = V_{pin1} + \left( R_o \times I_{uvp} (\mu A) \right) (V)$$

Practically ($V_{pin1}$ being neglected),

$$V_{uvp} = R_o \times I_{uvp} (\mu A) (V)$$

**Maximum On-Time Limitation**
As explained in PWM Latch, the maximum on-time is accurately controlled.

**Pin Protection**
All the pins are ESD protected.
Pin Numbers are Relevant to the PDIP-8 Version

In particular, a 11 V Zener diode is internally connected between the terminal and ground on the following pins: Feedback, _V_\text{control}, Oscillator, Current Sense, and Synchronization.

Figure 31. Synchronization Arrangement

SYNCHRONIZATION BLOCK

The MC33260 features two modes of operation:

- Free Running Discontinuous Mode: The power switch is turned on as soon as there is no current left in the inductor (Zero Current Detection). This mode is simply obtained by grounding the synchronization terminal (Pin 5).
- Synchronization Mode: This mode is set as soon as a signal crossing the 1.0 V threshold, is applied to the Pin 5. In this case, operation in free running can only be recovered after a new circuit startup. In this mode, the power switch cannot turn on before the two following conditions are fulfilled.

- Still, the zero current must have been detected.
- The precedent turn on must have been followed by (at least) one synchronization raising edge crossing the 1.0 V threshold.

In other words, the synchronization acts to prolong the power switch off time.

Consequently, a proper synchronized operation requires that the current cycle (on-time + inductor demagnetization) is shorter than the synchronization period. Practically, the inductor must be chosen accordingly. Otherwise, the system will keep working in free running discontinuous mode. Figure 36 illustrates this behavior.

It must be noticed that whatever the mode is, a 2.0 µs minimum off-time is forced. This delay limits the switching frequency in light load conditions.

OUTPUT SECTION

The output stage contains a totem pole optimized to minimize the cross conduction current during high speed operation. The gate drive is kept in a sinking mode whenever the Undervoltage Lockout is active. The rise and fall times have been controlled to typically equal 50 ns while loaded by 1.0 nF.

REFERENCE SECTION

An internal reference current source (I_{\text{ref}}) is trimmed to be ±4% accurate over the temperature range (the typical value is 200 µA). I_{\text{ref}} is the reference used for the regulation (I_{\text{regH}} = I_{\text{ref}}).

UNDERVOLTAGE LOCKOUT SECTION

An Undervoltage Lockout comparator has been implemented to guarantee that the integrated circuit is operating only if its supply voltage (V_{\text{CC}}) is high enough to enable a proper working. The UVLO comparator monitors the Pin 8 voltage and when it exceeds 11 V, the device gets active. To prevent erratic operation as the threshold is crossed, 2.5 V of hysteresis is provided.

The circuit off state consumption is very low: in the range of 100 µA @ V_{\text{CC}} = 5.0 V. This consumption varies versus V_{\text{CC}} as the circuit presents a resistive load in this mode.

THERMAL SHUTDOWN

An internal thermal circuitry is provided to disable the circuit gate drive and then to prevent it from oscillating, if the junction temperature exceeds 150°C typically.

The output stage is again enabled when the temperature drops below 120°C typically (30°C hysteresis).

http://onsemi.com
FOLLOWER BOOST

Traditional PFC preconverters provide the load with a fixed and regulated voltage that generally equals 230 V or 400 V according to the mains type (U.S., European, or universal).

In the “Follower Boost” operation, the preconverter output regulation level is not fixed but varies linearly versus the ac line amplitude at a given input power.

This technique aims at reducing the gap between the output and the input voltages to minimize the boost efficiency degradation.

Follower Boost Benefits

The boost presents two phases:

- The on-time during which the power switch is on. The inductor current grows up linearly according to a slope \( V_{\text{in}}/L_p \), where \( V_{\text{in}} \) is the instantaneous input voltage and \( L_p \) the inductor value.
- The off-time during which the power switch is off. The inductor current decreases linearly according the slope \( (V_o - V_{\text{in}})/L_p \), where \( V_o \) is the output voltage. This sequence that terminates when the current equals zero, has a duration that is inversely proportional to the gap between the output and input voltages. Consequently, the off-time duration becomes longer in follower boost.

Consequently, for a given peak inductor current, the longer the off time, the smaller power switch duty cycle and then its conduction dissipation. This is the first benefit of this technique: the MOSFET on-time losses are reduced.

The increase of the off time duration also results in a switching frequency diminution (for a given inductor value). Given that in practise, the boost inductor is selected big enough to limit the switching frequency down to an acceptable level, one can immediately see the second benefit of the follower boost: it allows the use of smaller, lighter and cheaper inductors compared to traditional systems.

Finally, this technique utilization brings a drastic system cost reduction by lowering the size and then the cost of both the inductor and the power switch.

Follower Boost Implementation

In the MC33260, the on-time is differently controlled according to the feedback current level. Two areas can be defined:

- When the feedback current is higher than \( I_{\text{regL}} \) (refer to regulation section), the regulation block output \( (V_{\text{control}}) \) is modulated to force the output voltage to a desired value.
- On the other hand, when the feedback current is lower than \( I_{\text{regL}} \) the regulation block output and therefore, the on-time are maximum. As explained in PWM Latch Section, the on-time is then inversely proportional to the output voltage square. The Follower Boost is active in these conditions in which the on-time is simply limited by the output voltage level. Note: In this equation, the Feedback Pin voltage \( (V_{\text{pin1}}) \) is neglected compared to the output voltage (refer to the PWM Latch Section).

\[
t_{\text{on}} = (t_{\text{on}})_{\text{max}} = \frac{C_{\text{pin3}} \times R_o^2}{K_{\text{osc}} \times V_o^2}
\]

where:

- \( C_{\text{pin3}} \) is the total oscillator capacitor (sum of the internal and external capacitors - \( C_{\text{int}} + C_T \)),
- \( K_{\text{osc}} \) is the ratio (oscillator swing over oscillator gain),
- \( V_o \) is the output voltage,
- \( R_o \) is the feedback resistor.
On the other hand, the boost topology has its own rule that dictates the on-time necessary to deliver the required power:

\[ t_{on} = \frac{4 \times L_p \times P_{in}}{V_{pk}^2} \]

where:
- \( V_{pk} \) is the peak ac line voltage,
- \( L_p \) is the inductor value,
- \( P_{in} \) is the input power.

Combining the two equations, one can obtain the Follower Boost equation:

\[ V_o = \frac{R_o}{2} \times \frac{C_{pin}^3}{K_{osc} \times L_p \times P_{in}} \times V_{pk} \]

Consequently, a linear dependency links the output voltage to the ac line amplitude at a given input power.

The behavior of the output voltage is depicted in Figures 34 and 35. In particular, Figure 35 illustrates how the output voltage converges to a stable equilibrium level. First, at a given ac line voltage, the on-time is dictated by the power demand. Then, the follower boost characteristic makes correspond one output voltage level to this on-time. Combining these two laws, it appears that the power level forces the output voltage.

One can notice that the system is fully stable:

- If an output voltage increase makes it move away from its equilibrium value, the on-time will immediately diminish according to the follower boost law. This will result in a delivered power decrease. Consequently, the supplied power being too low, the output voltage will decrease back.
- In the same way, if the output voltage decreases, more power will be transferred and then the output voltage will increase back.

**Mode Selection**

The operation mode is simply selected by adjusting the oscillator capacitor value. As shown in Figure 35, the output voltage first has an increasing linear characteristic versus the ac line magnitude and then is clamped down to the regulation value. In the traditional mode, the linear area must be rejected. This is achieved by dimensioning the oscillator capacitor so that the boost can deliver the maximum power while the output voltage equals its regulation level and this, whatever the given input voltage. Practically, that means that whatever the power and input voltage conditions are, the follower boost would generate output voltages values higher than the regulation level, if there was no regulation block.

In other words, if \((V_o)_{regL}\) is the low output regulation level:

\[ \frac{(V_o)_{regL}}{R_o} = \frac{C_T + C_{int}}{K_{osc} \times L_p \times (P_{in})_{max}} \times \frac{V_{pk}^2}{V_{pk}} \]

Consequently,

\[ C_T \geq -C_{int} + \frac{4 \times K_{osc} \times L_p \times (P_{in})_{max} \times (V_{o})_{regL}^2}{R_o^2 \times V_{pk}^2} \]

Using \(I_{regL}\) (regulation block current reference), this equation can be simplified as follows:

\[ C_T \geq -C_{int} + \frac{4 \times K_{osc} \times L_p \times (P_{in})_{max} \times I_{regL}^2}{V_{pk}^2} \]

In the Follower Boost case, the oscillator capacitor must be chosen so that the wished characteristics are obtained. Consequently, the simple choice of the oscillator capacitor enables the mode selection.
case no. 1: the turn on is delayed by the Zero Current Detection
cases no. 2 and no. 3: the turn on is delayed by the synchronization signal
case no. 4: the turn on is delayed by the minimum offtime (2 μs)

Figure 36. Typical Waveforms
### MAIN DESIGN EQUATIONS (Note 3)

<table>
<thead>
<tr>
<th>Equation</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{ac} = \frac{P_o}{\eta \times V_{ac}}$</td>
<td>$\eta$ (preconverter efficiency) is generally in the range of 90 - 95%.</td>
</tr>
<tr>
<td>$I_{pk\text{ max}} = \frac{2 \times \sqrt{2} \times P_o}{\eta \times V_{acLL}}$</td>
<td>$I_{pk\text{ max}}$ is the maximum inductor current.</td>
</tr>
<tr>
<td>$(\Delta V_{o\text{ pk-pk}}) = \frac{P_o}{2\pi \times f_{ac} \times C_o \times V_o}$</td>
<td>$f_{ac}$ is the ac line frequency (50 or 60Hz).</td>
</tr>
<tr>
<td>$L_p = \frac{2 \times t \times \left(\frac{V_o}{2} - V_{acLL}\right) \times V_{acLL}^2}{V_o \times V_{acLL} \times (I_{pk\text{ max}})^2}$</td>
<td>$t$ is the maximum switching period.</td>
</tr>
<tr>
<td>$(\text{Rs}<em>{on}) = \frac{1}{3} \times (R</em>{on}) \times (I_{pk\text{ max}})^2 \times \left[1 - \frac{1.2 \times V_{acLL}}{V_o}\right]$</td>
<td>$(R_{ds})_{on}$ is the MOSFET drain source on-time resistor.</td>
</tr>
<tr>
<td>$I_{d\text{ max}} = \frac{(P_o)<em>{max}}{(V_o)</em>{min}}$</td>
<td>The Average Diode Current depends on the power and on the output voltage.</td>
</tr>
<tr>
<td>$p_{R_{cs}} = \frac{1}{6} \times (\text{R}<em>{ds})</em>{on} \times (I_{pk\text{ max}})^2$</td>
<td>This formula indicates the required dissipation capability for $R_{cs}$ (current sense resistor).</td>
</tr>
<tr>
<td>$R_{OCP} = \frac{R_{cs} \times (I_{pk\text{ max}})}{0.205}$ (kΩ)</td>
<td>The overcurrent threshold is adjusted by $R_{OCP}$ at a given $R_{cs}$.</td>
</tr>
<tr>
<td>$V_o = \frac{R_{o}}{2} \times \sqrt{\frac{C_T + C_{int}}{R_{osc} \times L_p \times P_{in} \times V_{pk}}}$</td>
<td>The Follower Boost characteristic is adjusted by the $C_T$ choice.</td>
</tr>
<tr>
<td>$R_o = \frac{(V_o)<em>{reg} - V</em>{FB}}{I_{regH}} = \frac{V_o}{200}$ (MΩ)</td>
<td>The Traditional Mode is also selected by $C_T$.</td>
</tr>
<tr>
<td>$C_{int}$ is the oscillator pin internal capacitor.</td>
<td>The Follower Boost characteristic is adjusted by the $C_T$ choice.</td>
</tr>
</tbody>
</table>

3. The preconverter design requires the following characteristics specification:
   - $(V_o)_{reg}$: desired output voltage regulation level
   - $(\Delta V_{o\text{ pk-pk}})$: admissible output peak to peak ripple voltage
   - $P_o$: desired output power
   - $V_{ac}$: ac rms operating line voltage
   - $V_{acLL}$: minimum ac rms operating line voltage
   - $V_{FB}$: Feedback Pin voltage
Figure 37. 80 W Wide Mains Power Factor Corrector

**POWER FACTOR CONTROLLER TEST DATA**

<table>
<thead>
<tr>
<th>$V_{rms}$ (V)</th>
<th>$P_{in}$ (W)</th>
<th>PF (-)</th>
<th>$I_{fund}$ (mA)</th>
<th>Current Harmonic Distortion (% $I_{fund}$)</th>
<th>DC Output</th>
</tr>
</thead>
<tbody>
<tr>
<td>V</td>
<td>$I_{ref}$ (mA)</td>
<td>$I_{ovp}$ (mA)</td>
<td>$I_{ovp}$ (V)</td>
<td>$I_{ref}$ (V)</td>
<td>$I_{ref}$ (V)</td>
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<tr>
<td>90</td>
<td>88.2</td>
<td>0.991</td>
<td>990</td>
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<td>762</td>
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<td>0.05</td>
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<td>0.995</td>
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<td>0.03</td>
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<tr>
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<td>480</td>
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<td>0.16</td>
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<tr>
<td>220</td>
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<td>0.982</td>
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<td>15</td>
<td>0.5</td>
</tr>
<tr>
<td>240</td>
<td>85.3</td>
<td>0.975</td>
<td>359</td>
<td>16.5</td>
<td>0.7</td>
</tr>
<tr>
<td>260</td>
<td>84.0</td>
<td>0.967</td>
<td>330</td>
<td>18.8</td>
<td>0.7</td>
</tr>
</tbody>
</table>

*Measurements performed using Voltech PM1200 ac power analysis.
MC33260 V_{CC} SUPPLY VOLTAGE

In some applications, the arrangement shown in Figure 38 must be implemented to supply the circuit. A startup resistor is connected between the rectified voltage (or one-half wave) to charge the MC33260 V_{CC} up to its startup threshold (11 V typically). The MC33260 turns on and the V_{CC} capacitor (C_{pin8}) starts to be charged by the PFC transformer auxiliary winding. A resistor, r (in the range of 22 Ω) and a 15 V Zener should be added to protect the circuit from excessive voltages.

When the PFC preconverter is loaded by an SMPS, the MC33260 should preferably be supplied by the SMPS itself. In this configuration, the SMPS starts first and the PFC gets active when the MC33260 V_{CC} supplied by the power supply, exceeds the device startup level. With this configuration, the PFC preconverter doesn’t require any auxiliary winding and finally a simple coil can be used.

PCB LAYOUT

The connections of the oscillator and V_{control} capacitors should be as short as possible.

Figure 38. Circuit Supply Voltage

Figure 39. Preconverter Loaded by a Flyback SMPS: MC33260 V_{CC} Supply
### ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Device</th>
<th>Package</th>
<th>Shipping¹</th>
</tr>
</thead>
<tbody>
<tr>
<td>MC33260PG</td>
<td>PDIP-8 (Pb-Free)</td>
<td>50 Units / Rail</td>
</tr>
<tr>
<td>MC33260DG</td>
<td>SOIC-8 (Pb-Free)</td>
<td>98 Units / Rail</td>
</tr>
<tr>
<td>MC33260DR2G</td>
<td>SOIC-8 (Pb-Free)</td>
<td>2500 Units / Tape &amp; Reel</td>
</tr>
</tbody>
</table>

¹For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
MECHANICAL CASE OUTLINE

PACKAGING DIMENSIONS

PDIP-8
CASE 626–05
ISSUE P

DATE 22 APR 2015

NOTES:
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACK-
   AGE SEATED IN JEDEC SEATING PLANE GAUGE GS–3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH
   OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE
   NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM
   PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR
   TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE
   LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE
   LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE
   CORNERS).

<table>
<thead>
<tr>
<th>INCHES</th>
<th>MILLIMETERS</th>
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</thead>
<tbody>
<tr>
<td>A</td>
<td>0.210</td>
</tr>
<tr>
<td>A1</td>
<td>0.38</td>
</tr>
<tr>
<td>A2</td>
<td>0.195</td>
</tr>
<tr>
<td>b</td>
<td>0.022</td>
</tr>
<tr>
<td>b2</td>
<td>0.140</td>
</tr>
<tr>
<td>C</td>
<td>0.020</td>
</tr>
<tr>
<td>D</td>
<td>0.105</td>
</tr>
<tr>
<td>D1</td>
<td>0.015</td>
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<td>E1</td>
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<tr>
<td>e</td>
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<td>eB</td>
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<td>L</td>
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<td>M</td>
<td>10.16</td>
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</tbody>
</table>

*This information is generic. Please refer to
device data sheet for actual part marking.
Pb–Free indicator, “G” or microdot “*”,
may or may not be present.

DOCUMENT NUMBER: 98ASB42420B
DESCRIPTION: PDIP-8

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC–8 NB
CASE 751–07
ISSUE AK

DATE 16 FEB 2011

NOTES:
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

<table>
<thead>
<tr>
<th>MILLIMETERS</th>
<th>INCHES</th>
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</thead>
<tbody>
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</tr>
<tr>
<td>B</td>
<td>0.175  0.069</td>
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<tr>
<td>C</td>
<td>0.053  0.002</td>
</tr>
<tr>
<td>D</td>
<td>0.013  0.005</td>
</tr>
<tr>
<td>G</td>
<td>0.005  0.002</td>
</tr>
<tr>
<td>H</td>
<td>0.004  0.001</td>
</tr>
<tr>
<td>J</td>
<td>0.007  0.003</td>
</tr>
<tr>
<td>K</td>
<td>0.016  0.006</td>
</tr>
<tr>
<td>M</td>
<td>0.020  0.008</td>
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<tr>
<td>N</td>
<td>0.010  0.004</td>
</tr>
<tr>
<td>S</td>
<td>0.228  0.009</td>
</tr>
</tbody>
</table>

SOLDERING FOOTPRINT*  

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERAL MARKING DIAGRAM*

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “*”, may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2